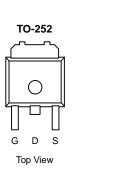
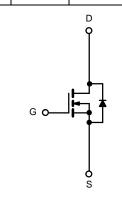


LR7811WC-VB Datasheet N-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A) ^{a, e}	Q _g (Typ)			
30	0.002 at V _{GS} = 10 V	100	72 nC			
30	0.003 at V _{GS} = 4.5 V	90	72110			





N-Channel MOSFET

FEATURES

- ٠ Trench Power MOSFET
- 100 % R_g and UIS Tested
- Compliant to RoHS Directive 2011/65/EU ٠

APPLICATIONS

- OR-ing
- Server
- DC/DC

Parameter		Symbol	Limit	Unit	
Drain-Source Voltage	V _{DS}	30	V		
Gate-Source Voltage		V _{GS}		± 20	
	T _C = 25 °C		100 ^{a, e}	A	
Continuous Drain Current (T _J = 175 °C)	T _C = 70 °C		80 ^e		
$Continuous Drain Current (1_j = 175 C)$	T _A = 25 °C	I _D	35.8 ^{b, c}		
	T _A = 70 °C		27 ^{b, c}		
Pulsed Drain Current	I _{DM}	300			
Avalanche Current Pulse		I _{AS}	39		
Single Pulse Avalanche Energy	L = 0.1 mH		94.8	mJ	
Continuous Source-Drain Diode Current	T _C = 25 °C		90 ^{a, e}	٨	
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	3.13 ^{b, c}	— A	
	T _C = 25 °C		235 ^a	w	
	T _C = 70 °C	P	165		
Maximum Power Dissipation	T _A = 25 °C	P _D	3.75 ^{b, c}		
	T _A = 70 °C		2.63 ^{b, c}		
Operating Junction and Storage Temperature Ra	T _J , T _{stg}	- 55 to 175	°C		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Тур.	Max.	Unit	
Maximum Junction-to-Ambient ^{b, d}	$t \le 10 \text{ sec}$	R _{thJA}	32	40	°C/W	
Maximum Junction-to-Case	Steady State	R _{thJC}	0.5	0.6	C/VV	

Notes:

a. Based on T_C = 25 °C. b. Surface mounted on 1" x 1" FR4 board.

a. t = 10 sec.
d. Maximum under steady state conditions is 90 °C/W.
e. Calculated based on maximum junction temperature. Package limitation current is 90 A.



SPECIFICATIONS ($T_J = 25 \text{ °C}$, Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static	Symbol	Test conditions	IVIIII.	тур.	IVIAA.	Onit
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = 250 μA	30	1		V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$			35		- mV/°(
V _{GS(th)} Temperature Coefficient	ΔV _{GS(th)} /T _J	I _D = 250 μA		- 7.5		
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \ \mu A$	1.5		2.5	V
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$	1.0		± 100	nA
	-033	$V_{\rm DS} = 30 \text{ V}, \text{ V}_{\rm GS} = 0 \text{ V}$			1	
Zero Gate Voltage Drain Current	I _{DSS}	$V_{\rm DS} = 30 \text{ V}, \text{ V}_{\rm GS} = 0 \text{ V}, \text{ T}_{\rm J} = 55 \text{ °C}$			10	μA
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 V, V_{GS} = 10 V$	90		10	A
	. ,	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 38.8 \text{ A}$		0.002		
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 37 \text{ A}$	0.002			Ω
Forward Transconductance ^a	9 _{fs}	$V_{DS} = 15 \text{ V}, \text{ I}_{D} = 38.8 \text{ A}$		160		S
Dynamic ^b	010					
Input Capacitance	C _{iss}			5201		pF
Output Capacitance	C _{oss}	V _{DS} = 15 V, V _{GS} = 0 V, f = 1 MHz		1525		
Reverse Transfer Capacitance	C _{rss}	20 00		770		
		V _{DS} = 15 V, V _{GS} = 10 V, I _D = 38.8 A		151	227	- nC
Total Gate Charge	Qg			71.5	103	
Gate-Source Charge	Q _{gs}	V_{DS} = 15 V, V_{GS} = 4.5 V, I_{D} = 28.8 A		30		
Gate-Drain Charge	Q _{gd}			24		
Gate Resistance	R _g	f = 1 MHz		1.4	2.1	Ω
Turn-On Delay Time	t _{d(on)}			18	27	
Rise Time	t _r	V_{DD} = 15 V, R_{L} = 0.625 Ω		11	17	- - - ns -
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 24$ A, V_{GEN} = 10 V, R_g = 1 Ω		70	105	
Fall Time	t _f			10	15	
Turn-On Delay Time	t _{d(on)}			55	83	
Rise Time	t _r	V_{DD} = 15 V, R_{L} = 0.67 Ω		180	270	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 22.5 \text{ A}, \text{ V}_{\text{GEN}} = 4.5 \text{ V}, \text{ R}_{\text{g}} = 1 \Omega$		55	83	
Fall Time	t _f			12	18	
Drain-Source Body Diode Characteristic	s			•	<u> </u>	
Continuous Source-Drain Diode Current	۱ _S	T _C = 25 °C			120	
Pulse Diode Forward Current ^a	I _{SM}				120	A
Body Diode Voltage	V _{SD}	I _S = 22 A		0.8	1.2	V
Body Diode Reverse Recovery Time	t _{rr}			52	78	ns
Body Diode Reverse Recovery Charge	Q _{rr}	L = 20.4 di/dt = 100.4 km		70.2	105	nC
Reverse Recovery Fall Time	t _a	I _F = 20 A, di/dt = 100 A/μs, T _J = 25 °C		27		
Reverse Recovery Rise Time	t _b	1		25		ns

Notes:

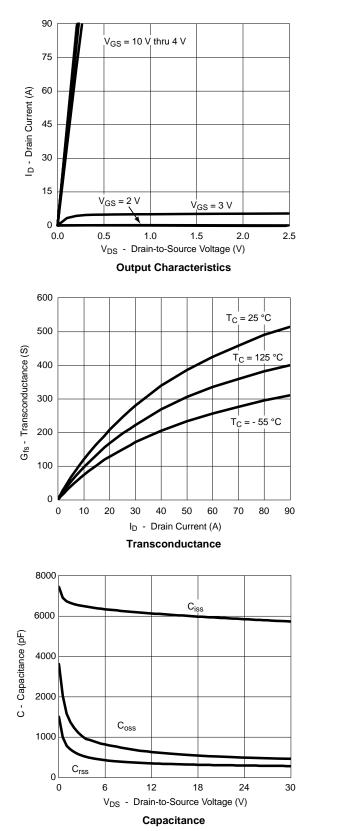
a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.

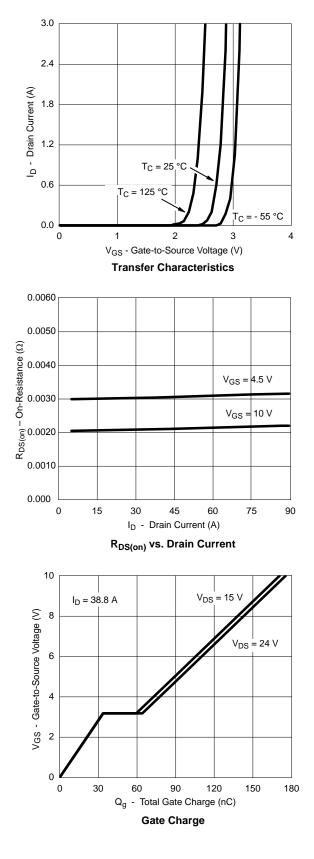
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Bsemi



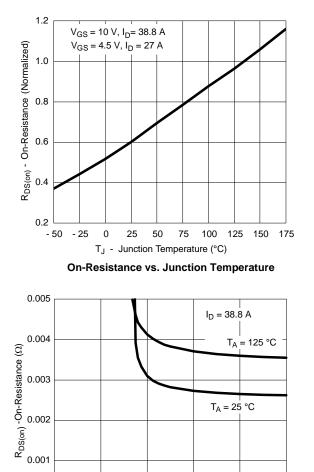


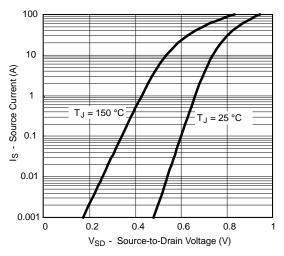
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



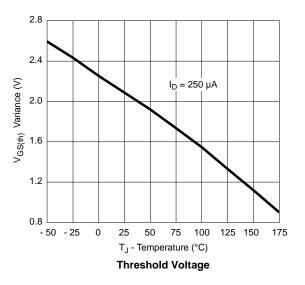


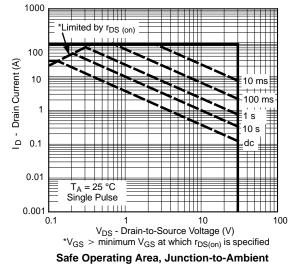
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)





Forward Diode Voltage vs. Temperature





0.000

0

2

4

6

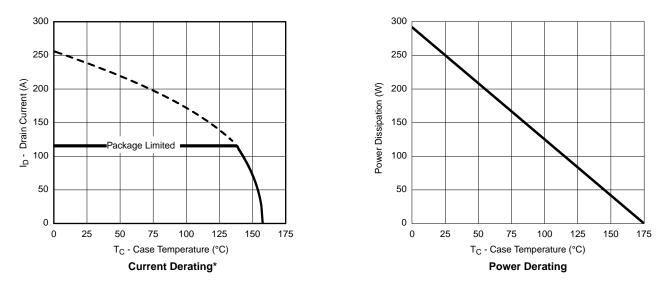
 V_{GS} - Gate-to-Source Voltage (V)

R_{DS(on)} vs. V_{GS} vs. Temperature

8

10





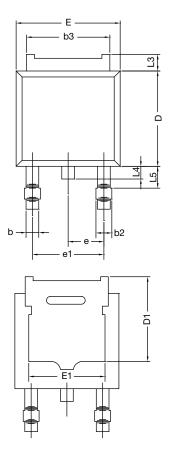
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

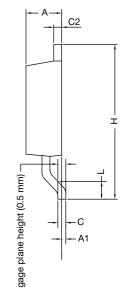
*The power dissipation P_D is based on $T_{J(max)} = 175$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.





TO-252AA CASE OUTLINE





	MILLIMETERS		INC	HES	
DIM.	MIN.	MAX.	MIN.	MAX.	
А	2.18	2.38	0.086	0.094	
A1	-	0.127	-	0.005	
b	0.64	0.88	0.025	0.035	
b2	0.76	1.14	0.030	0.045	
b3	4.95	5.46	0.195	0.215	
С	0.46	0.61	0.018	0.024	
C2	0.46	0.89	0.018	0.035	
D	5.97	6.22	0.235	0.245	
D1	5.21	-	0.205	-	
E	6.35	6.73	0.250	0.265	
E1	4.32	-	0.170	-	
Н	9.40	10.41	0.370	0.410	
е	2.28	BSC	0.090	BSC	
e1	4.56 BSC		0.180 BSC		
L	1.40	1.78	0.055	0.070	
L3	0.89	1.27	0.035	0.050	
L4	-	1.02	-	0.040	
L5	1.14	1.52	0.045	0.060	
ECN: X12-0247-Rev. M, 24-Dec-12 DWG: 5347					

Note

• Dimension L3 is for reference only.



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